Special Issue

Breakthroughs in Electromagnetic Sensing and Imaging: Cutting-Edge Techniques and Applications

Message from the Guest Editor

Electromagnetic sensing and imaging technologies have become essential tools in various scientific and engineering fields. These technologies utilize electromagnetic waves to detect, measure, and visualize physical properties, providing insights often beyond the reach of traditional methods. They are crucial in environmental monitoring, healthcare diagnostics, industrial automation, and communication systems. Recent innovations in sensor materials, fabrication techniques, and computational models have greatly enhanced the performance and capabilities of these systems.

This Special Issue aims to highlight pioneering research and advancements in electromagnetic sensing and imaging. The goal is to improve the accuracy, efficiency, and overall performance of sensing and imaging systems across various disciplines.

Researchers are invited to submit original, unpublished work covering a broad range of topics related to electromagnetic sensing and imaging. I look forward to your valuable contributions.

Guest Editor

Prof. Dr. Lulu Wang

1. School of Technology, Department of Engineering, Reykjavík University, Reykjavik, Iceland
2. Department of Physiology and Biomedical Engineering, Mayo Clinic, Rochester, MN, USA

Deadline for manuscript submissions

closed (30 June 2025)

Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed

mdpi.com/si/220877

Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

mdpi.com/journal/micromachines

Micromachines

an Open Access Journal by MDPI

Impact Factor 3.0
CiteScore 6.0
Indexed in PubMed

mdpi.com/journal/micromachines

About the Journal

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Editor-in-Chief

Prof. Dr. Ai-Qun Liu
1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

Author Benefits

High Visibility:

indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

Journal Rank:

JCR - Q2 (Instruments and Instrumentation) / CiteScore - Q1 (Mechanical Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 17.2 days after submission; acceptance to publication is undertaken in 1.9 days (median values for papers published in this journal in the first half of 2025).

MDPI